# SV2020A

Feature-rich 2-socket Server with Flexible I/O Options



# AMD EPYC<sup>TM</sup> Platform Solution

The dual AMD EPYC™ 7003 series processors, with up to 64 cores and 128 threads per socket, empower the system to support smoother multitasking and speed up your applications for faster business result.

## OCP 3.0 Add-On Card Support

The standard-compliant OCP 3.0 slot enables installation of a NIC card to provide high bandwidth and ultra-low latency for data intensive applications, bringing the server networking to the next level.

# Application

Hyperscale Data Center

Database

Software-defined Storage

Hyper-converged Infrastructure

Enterprise Application Server

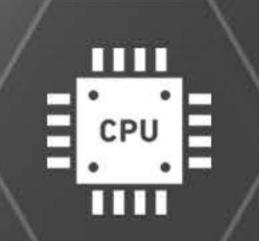
High Performance Computing

Big Data Analysis

Al and Machine Learning

# Flexible I/O Configurations

Designed to increase functionality for meeting your needs, the server supports diverse I/O configurations with up to 7 PCIe slots, allowing wide options of accelerators or I/O cards.



Two 3<sup>rd</sup> Generation AMD EPYC<sup>TM</sup> Processors



32 x DDR4 RDIMM



Supporting PCIe Gen4 x16, the product offers a superior bandwidth of 32 GB/s, twice that of PCIe Gen3 x16, to deliver outstanding expansion capability and I/O performance.





26 x 2.5" NVMe Drives



1+1 Redundancy, Platinum Level



2U Rackmount



# SV2020A

# Specifications



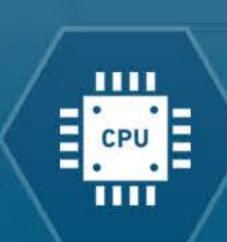
North America: +1 408-727-8060



Email: Sales@ingrasys.com

1 x OCP 3.0 NIC PCle Gen4 x16





#### Processor

Two 2<sup>nd</sup>/3<sup>rd</sup> Generation AMD EPYC<sup>TM</sup> Processors, up to 64 Cores, 225W (TDP)

32 x DDR4 3200MHz RDIMM/LRDIMM/



## Management

1 x ASPEED AST2500 BMC Support Intelligent Platform Management Interface v.2.0



### **PSUs**

**Expansion Slots** 

1 x PCle Gen4 x8 (LP)

2 x PCle Gen4 x16

4 x PCle Gen4 x8

1+1 Redundant 1600W Platinum **Power Supplies** 



#### Fans

6 x 60\*56mm



Certification FCC/UL/CB



### Storage

Memory

**3DS NVDIMM** 

Front & Rear

26 x 2.5" Hot-swap NVMe (Front: 24 + Rear: 2)

Internal

2 x SATA/NVMe M.2 (2280/22110)



#### Front Panel

1 x Power Button with LED 1 x UID Button with LED

1 x System Health LED



# Rear Panel

2 x USB 3.0 1 x Serial Port (RJ45 Type) 1 x RJ45 for BMC Dedicated Management 2 x RJ45 LAN Ports

1 x VGA Port



## Chassis Dimensions $I \leftarrow \rightarrow I \quad (H \times W \times D)$

3.42" x 17.6" x 28.4" / 87.0mm x 446.6mm x 721.2mm

Operating Temperature 10°C to 35°C (50°F to 95°F)

Non-operating Temperature -40°C to 70°C (-40°F to 158°F)

Operating Relative Humidity 8% to 90%RH

Non-operating Relative Humidity 5% to 90%RH



#### TPM

1 x TPM 2.0 Module



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